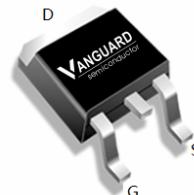


Features

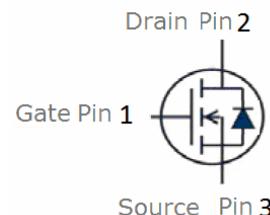
- N-Channel
- Enhancement mode
- Very low on-resistance @ $V_{GS}=4.5$ V
- Fast Switching
- Pb-free lead plating; RoHS compliant

V_{DS}	60	V
$R_{DS(on),typ}@VGS=10V$	68	$m\Omega$
$R_{DS(on),typ}@VGS=4.5V$	85	$m\Omega$
I_D	15	A

TO-252



Part ID	Package Type	Marking	Tape and reel information
VSD080N06MS	TO-252	080N06	2500pcs/reel



Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	60	V
V_{GS}	Gate-Source voltage	± 16	V
I_D	Continuous drain current@ $V_{GS}=10V$	$T_C=25^\circ C$	A
		$T_A=70^\circ C$	A
I_{DM}	Pulse drain current tested ①	$T_C=25^\circ C$	A
P_D	Maximum power dissipation	$T_C=25^\circ C$	W
I_S	Diode Continuous Forward Current	$T_C=25^\circ C$	A
EAS	Avalanche energy, single pulsed ②	$I_D=10A$	mJ
T_J	Maximum Junction Temperature	175	°C
T_{STG}	Storage and operating temperature range	-55 to 175	°C

Thermal characteristics

$R_{\theta JA}$	Thermal Resistance Junction-Ambient	60	°C/W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	5	°C/W

Typical Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 16\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	2.0	3.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$	--	68	80	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=5\text{A}$	--	85	100	$\text{m}\Omega$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=1.8\text{A}$	3	--	--	S
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	435	--	pF
C_{oss}	Output Capacitance		--	40	--	pF
C_{rss}	Reverse Transfer Capacitance		--	28	--	pF
Q_{g}	Total Gate Charge	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=1\text{A}, V_{\text{GS}}=10\text{V}$	--	6	--	nC
Q_{gs}	Gate-Source Charge		--	1.7	--	nC
Q_{gd}	Gate-Drain Charge		--	1.5	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=30\text{V}, I_{\text{D}}=1\text{A}, R_{\text{G}}=6.8\Omega, V_{\text{GS}}=4.5\text{V}$	--	6	--	nS
t_{r}	Turn-on Rise Time		--	15	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	16	--	nS
t_{f}	Turn-Off Fall Time		--	10	--	nS
Source- Drain Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=10\text{A}, V_{\text{GS}}=0\text{V}$	--	0.95	1.20	V

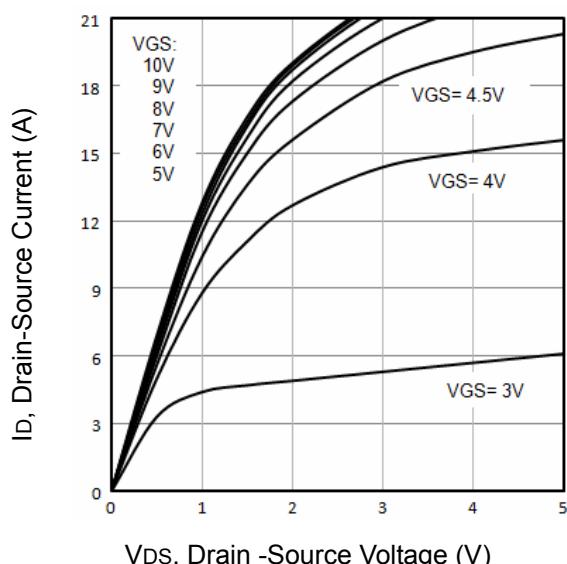
NOTE:

① Repetitive rating; pulse width limited by max. junction temperature

② Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.1\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 10\text{A}$, $V_{GS} = 10\text{V}$. Part not recommended for use above this value.

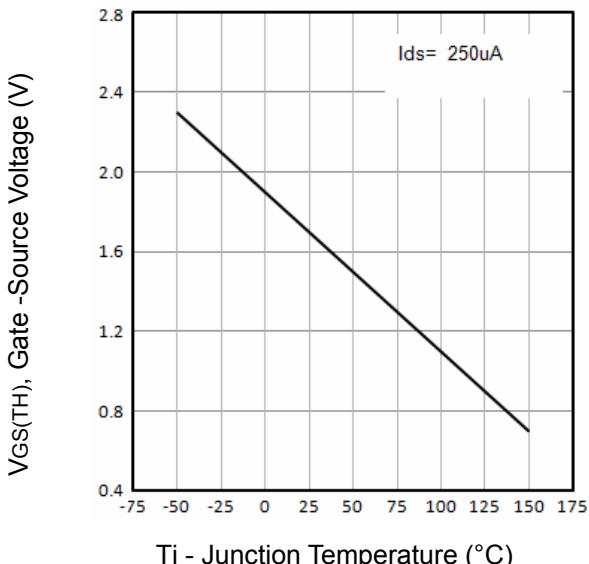
③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Typical Characteristics



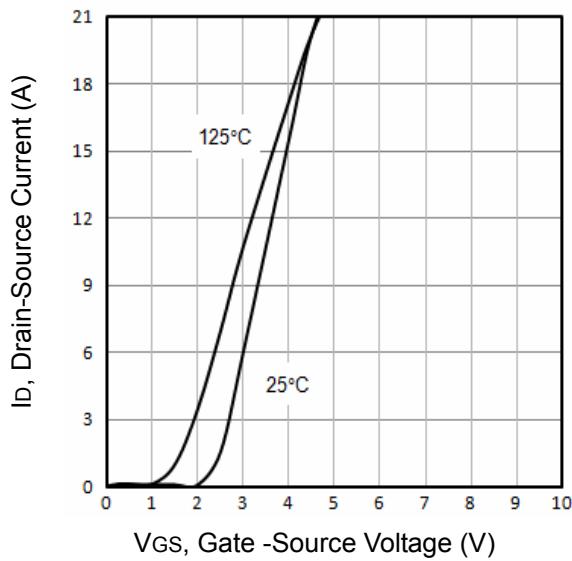
V_{DS}, Drain -Source Voltage (V)

Fig1. Typical Output Characteristics



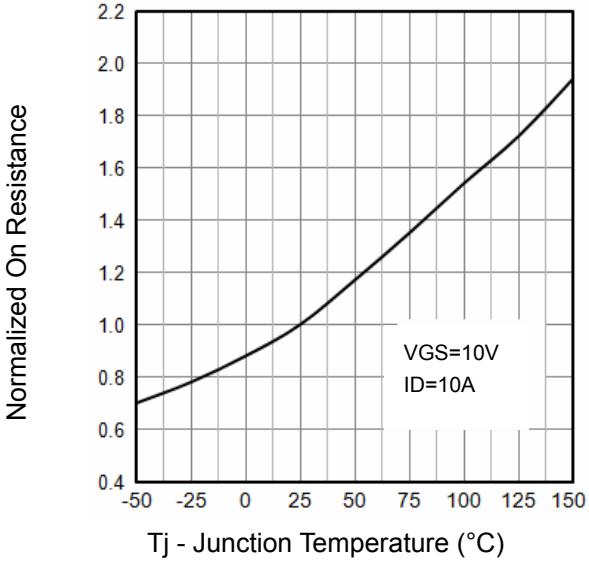
T_j - Junction Temperature (°C)

Fig2. Threshold Voltage Vs. Temperature



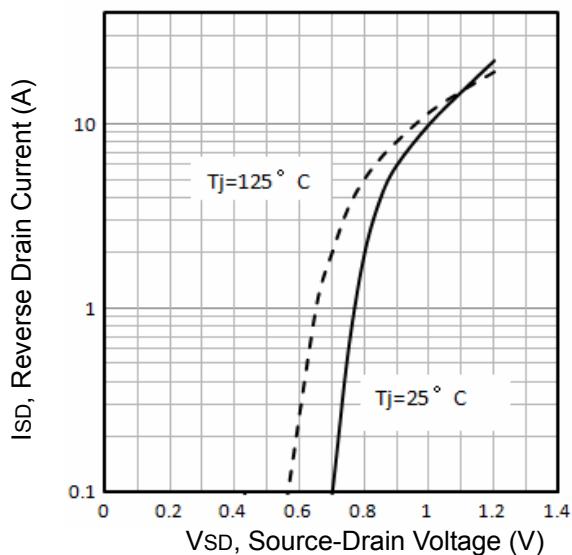
V_{GS}, Gate -Source Voltage (V)

Fig3. Typical Transfer Characteristics



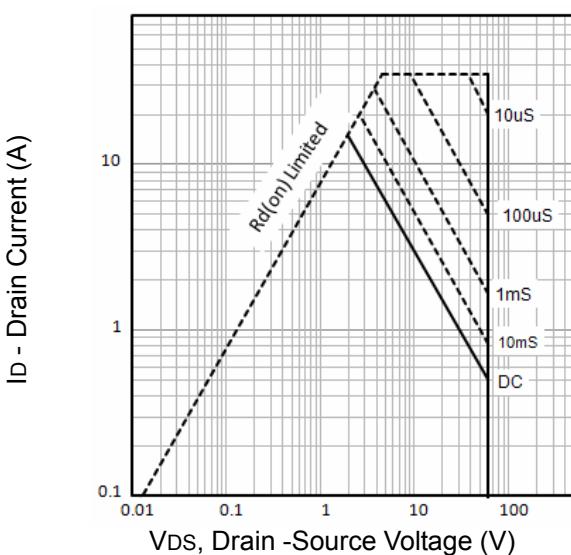
T_j - Junction Temperature (°C)

Fig4. Normalized On-Resistance Vs. Temperature



V_{SD}, Source-Drain Voltage (V)

Fig5. Typical Source-Drain Diode Forward Voltage



V_{DS}, Drain -Source Voltage (V)

Fig6. Maximum Safe Operating Area

Typical Characteristics

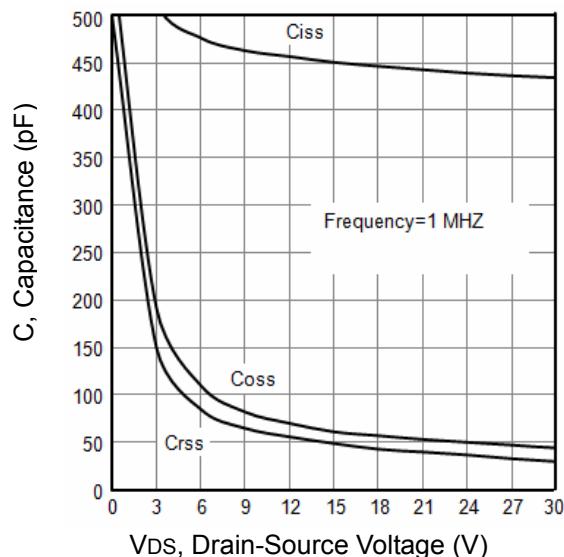


Fig7. Typical Capacitance Vs. Drain-Source Voltage

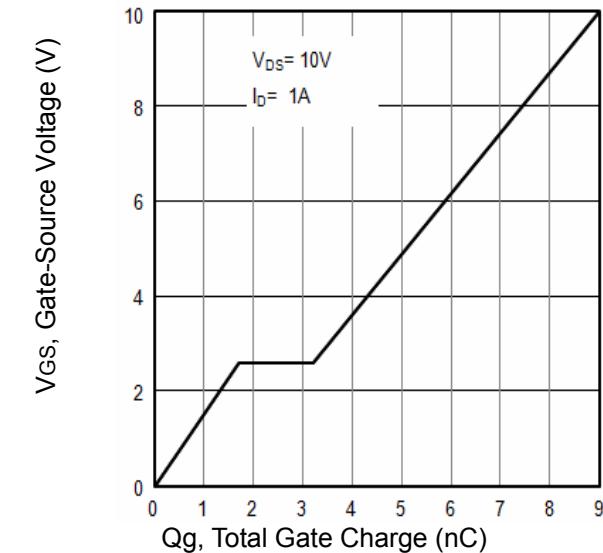


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

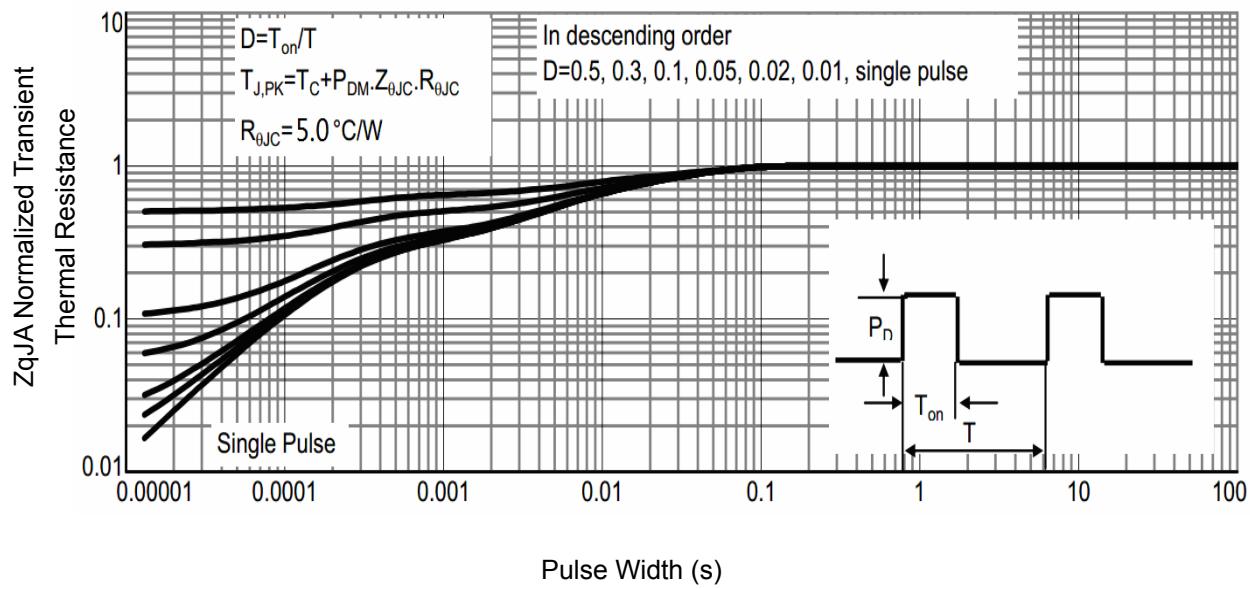


Figure 9: Normalized Maximum Transient Thermal

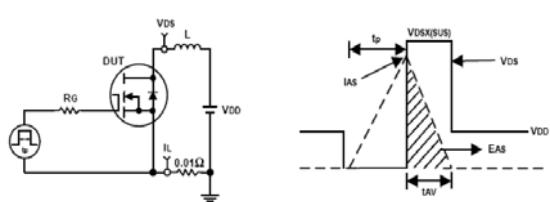


Fig10. Unclamped Inductive Test Circuit and waveforms

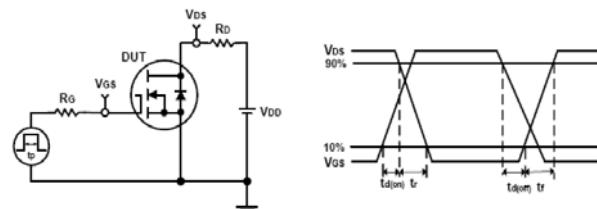
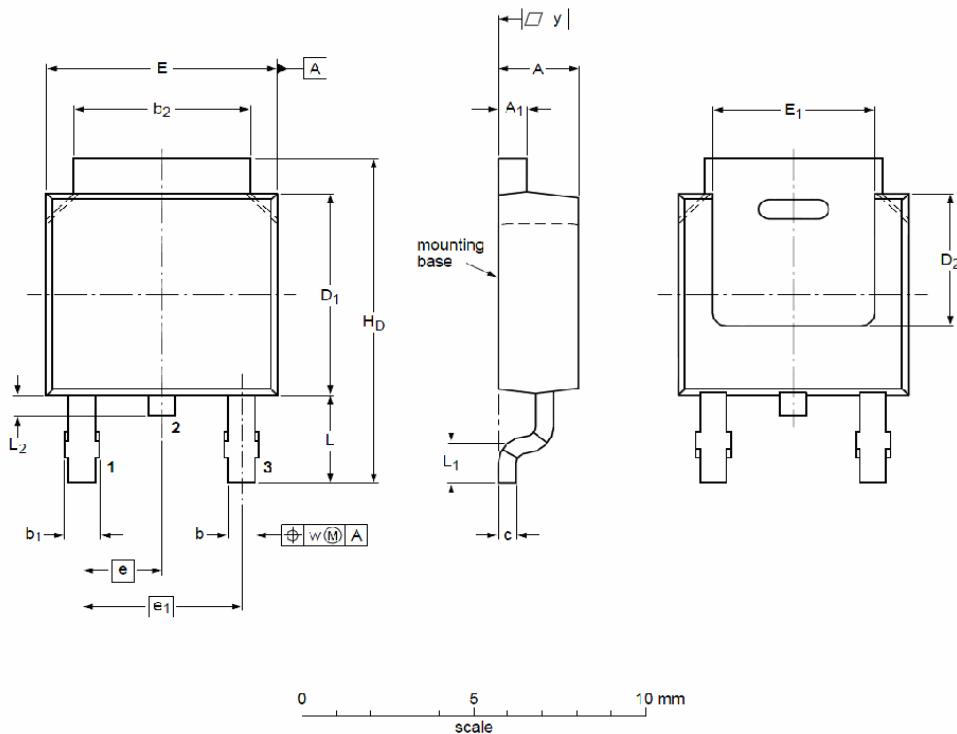


Fig11. Switching Time Test Circuit and waveforms

TO-252 Package Outline



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.22	2.30	2.38	A₁	0.46	0.58	0.93
b	0.71	0.79	0.89	b₁	0.90	0.98	1.10
b₂	5.00	5.30	5.46	c	0.20	0.40	0.56
D₁	5.98	6.05	6.22	D₂	--	4.00	--
E	6.47	6.60	6.73	E₁	5.10	5.28	5.45
e	--	2.28	--	e₁	--	4.57	--
H_D	9.60	10.08	10.40	L	2.75	2.95	3.05
L₁	--	0.50	--	L₂	0.80	0.90	1.10
w	--	0.20	--	y	0.20	--	--

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